200mW, 0.37V Schottky Barrier Diode

FEATURES

- Designed for mounting on small surface
- Low Capacitance
- Low forward voltage drop
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Adapters
- For switching power supply
- Low stored charge
- Inverter

MECHANICAL DATA

- Case: SOD-323
- Molding compound meets UL 94 V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Terminal: Matte Au plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: Indicated by cathode band
- Weight: 0.004grams (approximately)

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	PART NUMBER	UNIT	
Marking code on the device		5		
Repetitive peak reverse voltage	V _{RRM}	40	V	
Forward current	I _{F(AV)}	30	mA	
Non-repetitive peak forward surge current @ t = 8.3ms	I _{FSM}	0.2	А	
Junction temperature range	TJ	-45 to +125	°C	
Storage temperature range	T _{STG}	-45 to +125	°C	

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-ambient thermal resistance (1)	$R_{\Theta J A}$	500	°C/W	

1

Notes:

1. Valid provided that terminals are kept at ambient temperatureulse





HALOGEN







Taiwan Semiconductor

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage per diode (1)	I _F = 1mA, T _J = 25°C	V _F		0.37	V
Reverse current @ rated V_R per diode $^{(2)}$	V _R =30V T _J = 25°C	I _R		0.5	μΑ
Junction capacitance	1 MHz, V _R =0V	CJ	2	2	ρF

Notes:

1. Pulse test with PW=0.3 ms

2. Pulse test with PW=30 ms

ORDERING INFORMATION				
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
RB751V-40 (Note 1)	RR	G	SOD-323	3K / 7" Reel

Notes:

1. Whole series with green compound

EXAMPLE				
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
RB751V-40 RRG	RB751V-40	RR	G	Green compound



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$





Fig.1 Typical Forward Characteristics





Fig.4 Typical Junction Capacitance





PACKAGE OUTLINE DIMENSION



DIM	Unit	(mm)	nm) Unit(inch)	
DIM.	Min	Max	Min	Max
А	1.150	1.400	0.045	0.055
В	2.300	2.700	0.091	0.106
С	0.250	0.450	0.010	0.018
D	1.600	1.800	0.063	0.071
Е	0.800	1.000	0.031	0.039
F	0.050	0.177	0.002	0.007
G	0.475 REF		0.019	REF
Н		0.100		0.004

SUGGEST PAD LAYOUT



DIM	Unit(mm)	Unit(inch)	
DIM.	Тур.	Тур.	
A	0.63	0.025	
В	0.83	0.033	
С	1.60	0.063	
D	2.86	0.113	



Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.